

REMARKS

This is in response to the Office Action dated March 9, 2005. Non-elected claims 10-18 have been canceled, without prejudice in view of the Restriction Requirement. New claims 19-20 have been added. Thus, claims 1-9 and 19-20 are now pending.

The figures have been amended as suggested by the Examiner. See the Office Action at pages 3-4.

Applicant notes with appreciation the Examiner's indication that claims 5-8 contain allowable subject matter. In this regard, claim 5 has been essentially rewritten in independent form. Thus, claims 5-8 are now in condition for allowance.

Claim 1 stands rejected under 35 U.S.C. Section 102(b) as being allegedly anticipated by Lien. This Section 102(b) rejection is respectfully traversed for at least the following reasons.

Claim 1 as amended requires that "the protective film bridges adjacent ones of said remaining ones of the plurality of wires at least in a region overlapping with the bonding pad so that a void is formed in the protective film between the adjacent ones of said remaining ones of the plurality of wires." For example, and without limitation, see voids 16 in Figs. 1-2 of the instant application, which are advantageous for the example reasons discussed on page 29 of the specification. Such voids are advantageous, for example, in that they serve as air springs to absorb applied stress on the protective film when mounting chips (e.g., pg. 29, liens 17-22). The cited art fails to disclose or suggest the aforesaid underlined features of claim 1.

Lien (US 5,989,991) in Fig. 6 discloses no voids in alleged protective film 308 between adjacent wires 311. Thus, Lien is entirely unrelated to the invention of amended claim 1.

Claim 20 requires that "the protective film formed on said remaining ones of the plurality of wires is bridged between adjacent ones of said remaining ones of the plurality of wires at least

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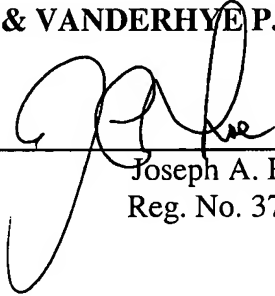
in a region overlapping with the bonding pad so that a void is formed in the protective film at least between adjacent first and second of the remaining ones of the plurality of wires at least in a region overlapping with the bonding pad." Again, Lien fails to disclose or suggest this feature of claim 20.

It is thus respectfully requested that all rejections be withdrawn. All claims are in condition for allowance. If any minor matter remains to be resolved, the Examiner is invited to telephone the undersigned with regard to the same.

Respectfully submitted,

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AMENDMENTS TO THE DRAWINGS

The attached sheets of drawings includes changes to Figs. 26-34. These sheets, which include Figs. 26-34, replace the original sheets including Figs. 26-34. In particular, Figs. 26-34 have been labeled “prior art.”

Attachment: Replacement Sheets